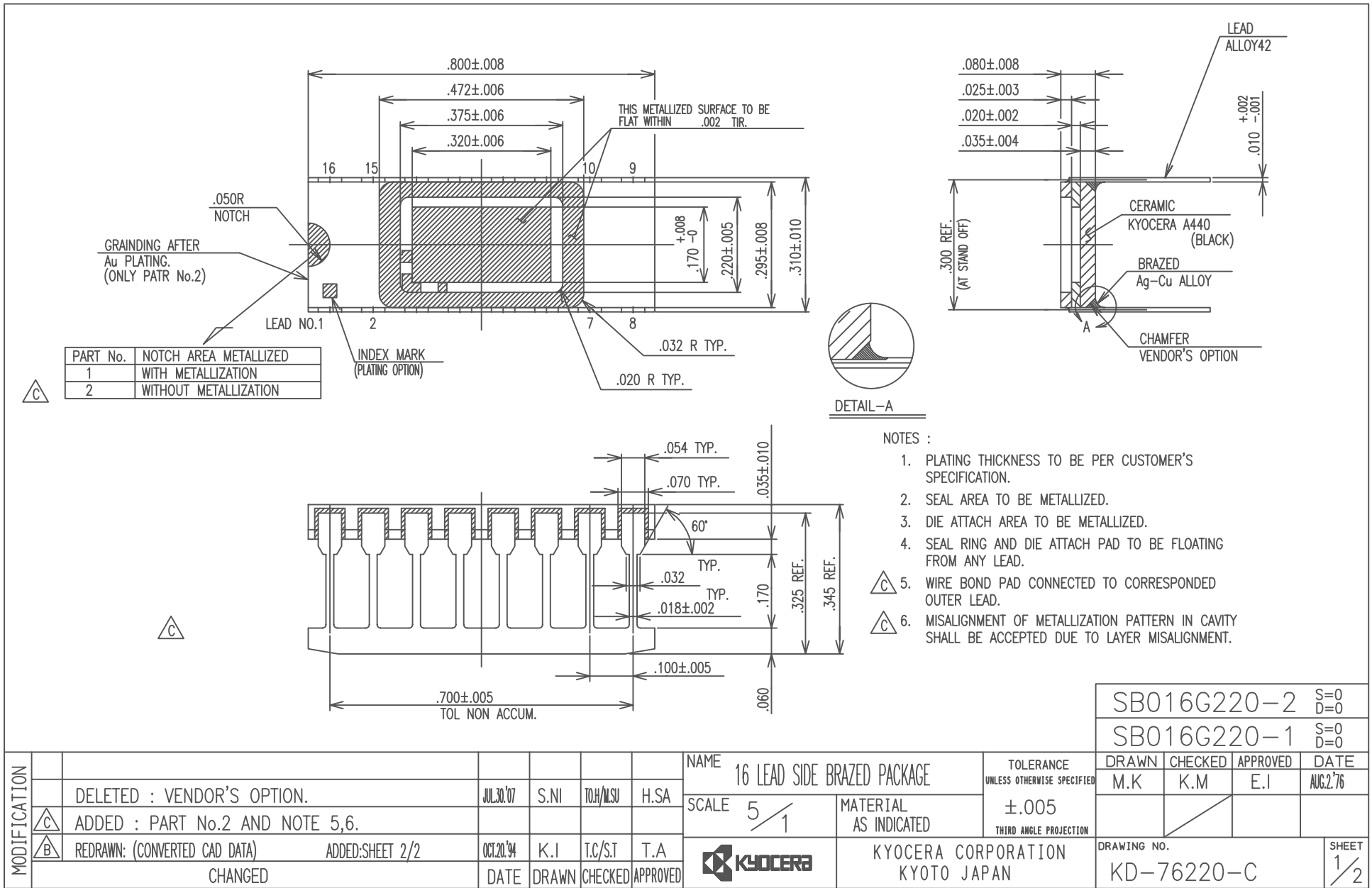


SSM P/N CSB01655



PART No.	NOTCH AREA METALLIZED WITH METALLIZATION
1	WITH METALLIZATION
2	WITHOUT METALLIZATION

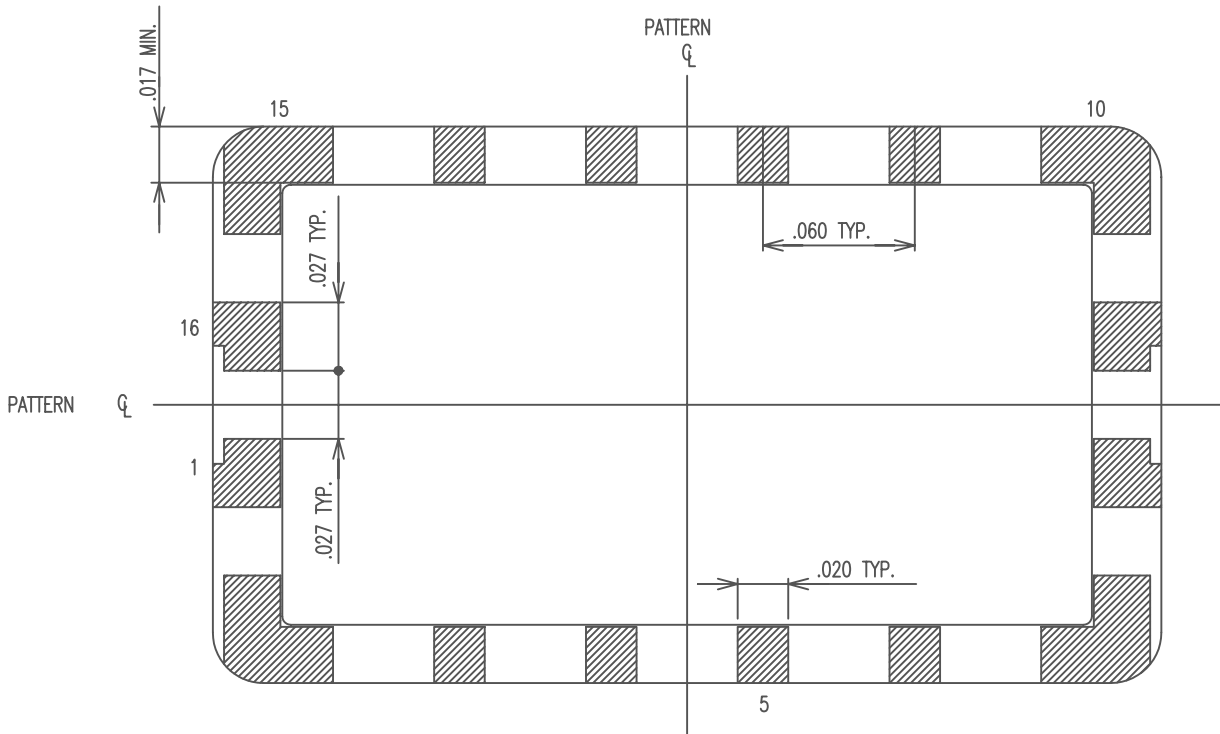
- NOTES :
1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
 2. SEAL AREA TO BE METALLIZED.
 3. DIE ATTACH AREA TO BE METALLIZED.
 4. SEAL RING AND DIE ATTACH PAD TO BE FLOATING FROM ANY LEAD.
 5. WIRE BOND PAD CONNECTED TO CORRESPONDED OUTER LEAD.
 6. MISALIGNMENT OF METALLIZATION PATTERN IN CAVITY SHALL BE ACCEPTED DUE TO LAYER MISALIGNMENT.

MODIFICATION	DELETED : VENDOR'S OPTION.	JUL.30'07	S.NI	TO.H/MSU	H.SA
	ADDED : PART No.2 AND NOTE 5,6.				
	REDRAWN: (CONVERTED CAD DATA)	OCT.20'94	K.I	T.C/S.T	T.A
	CHANGED	DATE	DRAWN	CHECKED	APPROVED

NAME	16 LEAD SIDE BRAZED PACKAGE
SCALE	5/1
MATERIAL	AS INDICATED
TOLERANCE	±.005
UNLESS OTHERWISE SPECIFIED	
THIRD ANGLE PROJECTION	
KYOCERA CORPORATION KYOTO JAPAN	

SB016G220-2				S=0
SB016G220-1				D=0
DRAWN	CHECKED	APPROVED	DATE	
M.K	K.M	E.I	AUG.2'76	
DRAWING NO.				SHEET
KD-76220-C				1/2





BONDING PATTERN

MODIFICATION						NAME	16 LEAD SIDE BRAZED PACKAGE	TOLERANCE	DRAWN	CHECKED	APPROVED	DATE
						SCALE	20/1	UNLESS OTHERWISE SPECIFIED	K.I	T.C/S.F	T.A	OCT.20.'94
						MATERIAL		THIRD ANGLE PROJECTION				
	△ REDRAWN:(CONVERTED CAD DATA)	OCT.20.'94	K.I	T.C/S.F	T.A		KYOCERA CORPORATION KYOTO JAPAN	DRAWING NO.	KD-76220-C		SHEET	2/2
	CHANGED	DATE	DRAWN	CHECKED	APPROVED							



